100 kPa On-Chip Temperature Compensated & Calibrated Silicon Pressure Sensors

MPXM2102 SERIES

COMPENSATED AND CALIBRATED PRESSURE SENSOR
0 TO 100 kPA (0 TO 14.5 psi)
40 mV FULL SCALE SPAN (TYPICAL)

The MPXM2102 device is a silicon piezoresistive pressure sensors providing a highly accurate and linear voltage output - directly proportional to the applied pressure. The sensor is a single, monolithic silicon diaphragm with the strain gauge and a thin-film resistor network integrated on-chip. The chip is laser trimmed for precise span and offset calibration and temperature compensation.

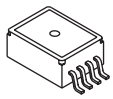
Features

- Temperature Compensated Over 0°C to +85°C
- Available in Easy-to-Use Tape & Reel
- Ratiometric to Supply Voltage
- Gauge Ported and Non Ported Options

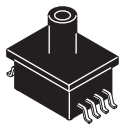
Typical Applications

- Pump/Motor Controllers
- Robotics
- Level Indicators
- Medical Diagnostics
- Pressure Switching
- Barometers
- Altimeters

MPAK PACKAGES



MPXM2102D/A
CASE 1320-02



MPXM2102GS/AS
CASE 1320A-02

ORDERING INFORMATION					
Device Type	**Options**	**Case No.**	**MPX Series Order No.**	**Packing Options**	**Device Marking**
Non-ported	Gauge	1320	MPXM2102D	Rails	MPXM2102D
	Gauge	1320	MPXM2102DT1	Tape & Reel	MPXM2102D
	Absolute	1320	MPXM2102A	Rails	MPXM2102A
	Absolute	1320	MPXM2102AT1	Tape & Reel	MPXM2102A
Ported	Gauge, Axial Port	1320A	MPXM2102GS	Rails	MPXM2102G
	Gauge, Axial Port	1320A	MPXM2102GST1	Tape & Reel	MPXM2102G
	Absolute, Axial Port	1320A	MPXM2102AS	Rails	MPXM2102A
	Absolute, Axial Port	1320A	MPXM2102AST1	Tape & Reel	MPXM2102A

Pin Number			
1	Gnd	3	V_S
2	$+V_{out}$	4	$-V_{out}$

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Figure 1 shows a block diagram of the internal circuitry on the stand-alone pressure sensor chip.

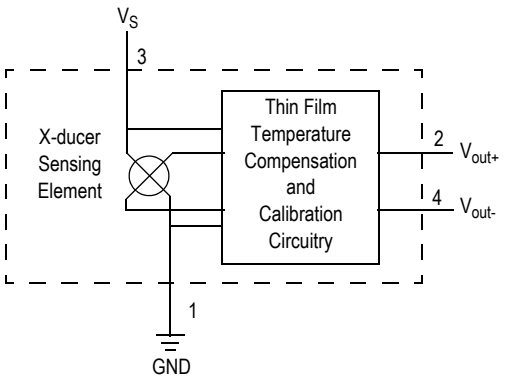


Figure 1. Temperature Compensated Pressure Sensor Schematic

VOLTAGE OUTPUT VERSUS APPLIED DIFFERENTIAL PRESSURE

The differential voltage output of the sensor is directly proportional to the differential pressure applied.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side relative to the vacuum side. Similarly, output voltage increases as increasing vacuum is applied to the vacuum side relative to the pressure side.

Table 1. Maximum Ratings[1]

Rating	Symbol	Value	Unit
Maximum Pressure	P_{max}	200	kPa
Storage Temperature	T_{stg}	-40 to +125	°C
Operating Temperature	T_A	-40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Table 2. Operating Characteristics (V_S = 10 Vdc, T_A = 25°C.)

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure Range[1]		P_{OP}	0	—	100	kPa
Supply Voltage[2]		V_S	—	10	16	Vdc
Supply Current		I_o	—	6.0	-	mAdc
Full Scale Span[3]		V_{FSS}	38.5	40	41.5	mV
Offset[4]	MPXM2102D/G Series MPXM2102A Series	V_{off}	-1.0 -2.0	— —	1.0 2.0	mV
Sensitivity		$\Delta V/\Delta P$	—	0.4	—	mV/kPa
Linearity[5]	MPXM2102D/G Series MPXM2102A Series	— —	-0.6 -1.0	— —	0.4 1.0	$\%V_{FSS}$
Pressure Hysteresis[5] (0 to 100 kPa)		—	—	±0.1	—	$\%V_{FSS}$
Temperature Hysteresis[5] (-40°C to +125°C)		—	—	±0.5	—	$\%V_{FSS}$
Temperature Effect on Full Scale Span[5]		TCV_{FSS}	-2.0	—	2.0	$\%V_{FSS}$
Temperature Effect on Offset[5]		TCV_{off}	-1.0	—	1.0	mV
Input Impedance		Z_{in}	1000	—	2500	Ω
Output Impedance		Z_{out}	1400	—	3000	Ω
Response Time[6] (10% to 90%)		t_R	—	1.0	—	ms
Warm-Up		—	—	20	—	ms
Offset Stability[7]		—	—	±0.5	—	$\%V_{FSS}$

1. 1.0 kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.
3. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
4. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
5. Accuracy (error budget) consists of the following:
   - Linearity: Output deviation from a straight line relationship with pressure, using end point method, over the specified pressure range.
   - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
   - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
   - TcSpan: Output deviation at full rated pressure over the temperature range of 0 to 85°C, relative to 25°C.
   - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C, relative to 25°C.
6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off}$ + sensitivity x P over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 2) or (2) a least squares best line fit. While a least squares fit gives the "best case" linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the "worst case" error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. The specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

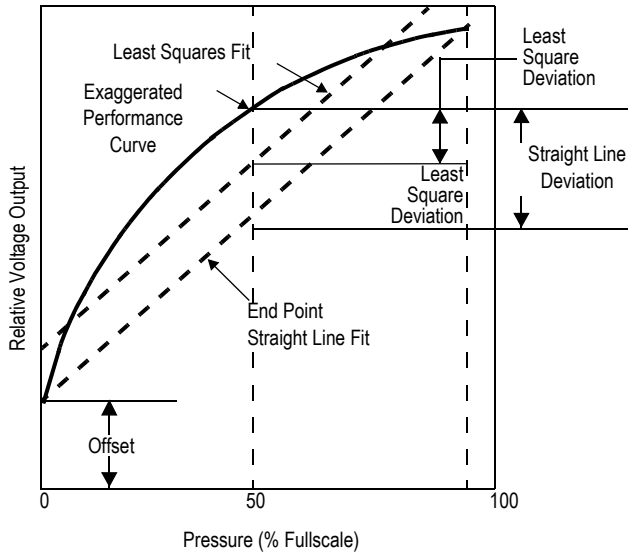


Figure 2. Linearity Specification Comparison

ON-CHIP TEMPERATURE COMPENSATION AND CALIBRATION

Figure 3 shows the minimum, maximum and typical output characteristics of the MPXM2120 series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

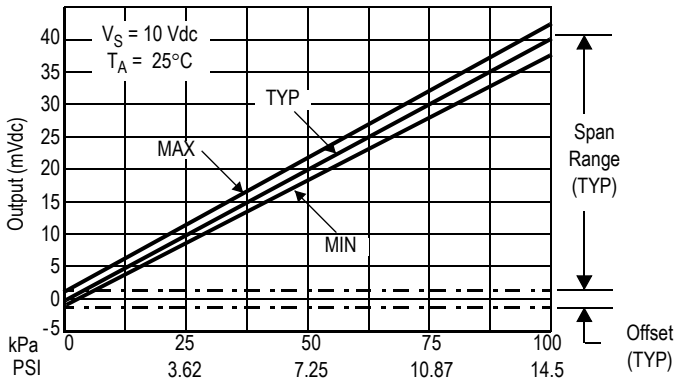
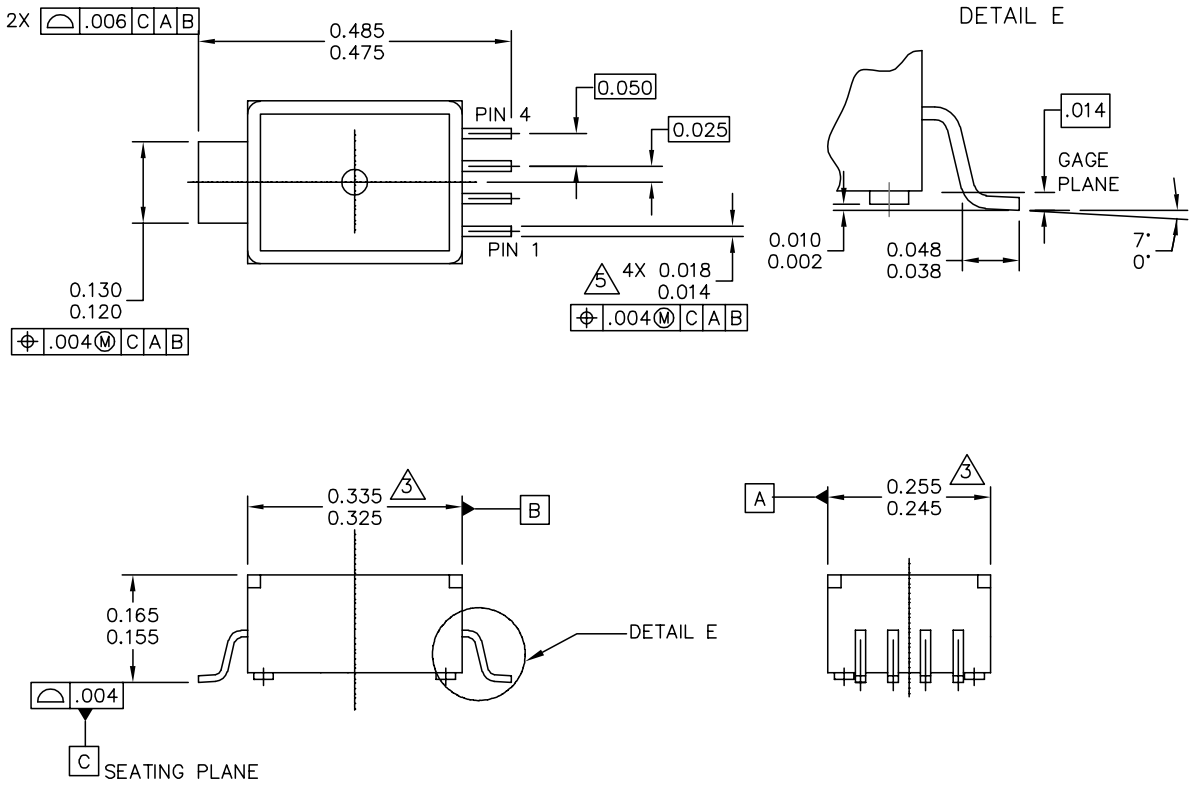


Figure 3. Output versus Pressure Differential

PACKAGE DIMENSIONS



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	CASE NUMBER: 1320-02	22 JUL 2005
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CASE 1320-02
ISSUE B

PACKAGE DIMENSIONS

NOTES:

1. DIMENSIONS ARE IN INCHES.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

PIN 1: GND
PIN 2: +Vout
PIN 3: Vs
PIN 4: −Vout

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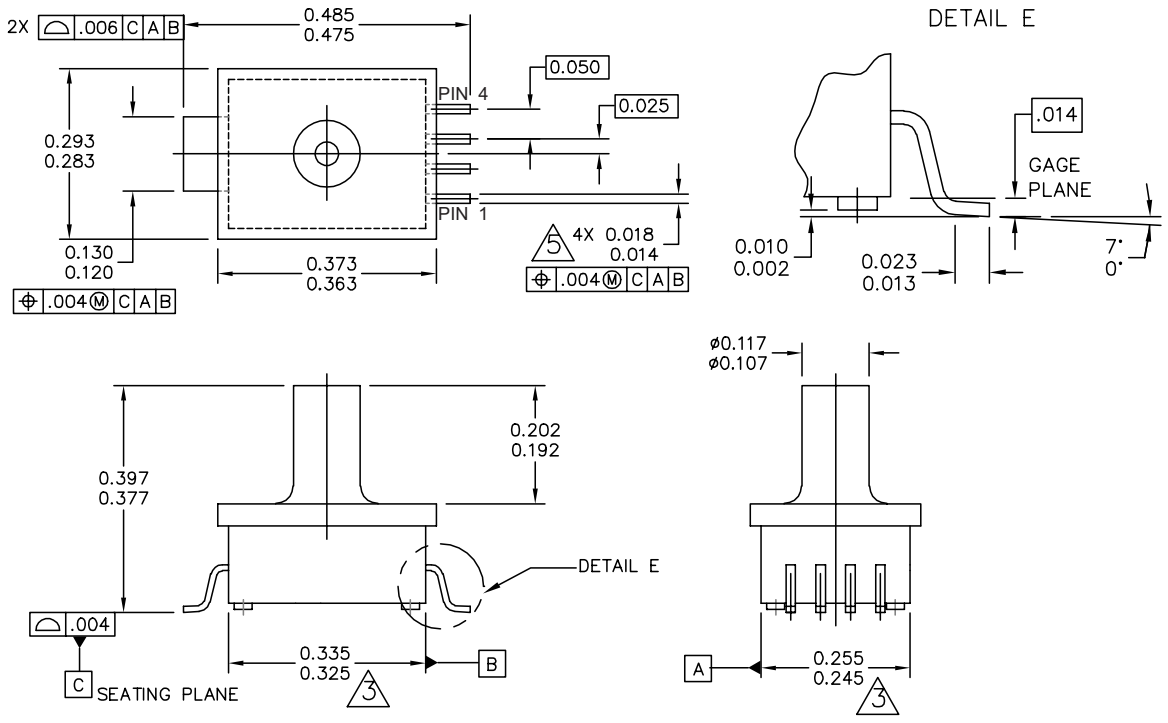
CASE 1320-02
ISSUE B

PACKAGE DIMENSIONS



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CASE 1320A-02
ISSUE A

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CASE 1320A-02
ISSUE A

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